

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (currently amended): A method for producing an assembly of substrates comprising:

(B3) dispensing a liquid polymeric material [between] on one of a conducting surface on a first substantially planar substrate and a conducting surface on a second substantially planar substrate, the liquid polymeric being disposed inwardly from the edges of the first and the second substrate;

pressing the liquid polymeric material between the first and the second substrate so that the liquid polymeric material flows towards the edges of the first substrate and the second substrate; and

curing the liquid polymeric material.

Claim 2 (original): The method of Claim 1 further comprising contacting the conducting surface on the first substrate and the conducting surface on the second substrate after pressing the liquid polymeric material between the first substrate and the second substrate.

Claim 3 (original): The method of Claim 1 wherein the liquid polymeric material is dispensed on dies present on the first or second substrate.

Claim 4 (original): The method of Claim 1 wherein at least one of the substrates has a planar surface area of at least about 36 sq. inches.

Claim 5 (original): The method of Claim 1 wherein said conducting surface of said first planar substrate includes first conductive pads, and said conducting surface of said second planar substrate includes second conductive pads and solder bumps disposed on said second conductive pads.

Claim 6 (original): The method of Claim 5 wherein said solder bumps comprise a solder material fluxing agent.

Claim 7 (original): The method of Claim 6 wherein said liquid polymeric material comprises a polymer fluxing agent.

Claim 8 (original): The method of Claim 1 wherein said liquid polymeric material comprises a polymer fluxing agent.

Claim 9 (original): The method of Claim 5 wherein said solder bumps includes no solder material fluxing agent and said liquid polymeric material comprises a polymer fluxing agent.

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Claim 10 (previously presented): The method of Claim 7 wherein said polymer fluxing agent comprises a beta phenylacid and/or a beta phenylhydroxyacid.

Claim 11 (original): The method of Claim 9 wherein said polymer fluxing agent comprises a beta phenylacid and/or a beta phenylhydroxyacid.

Claim 12 (original): The method of Claim 10 wherein said beta phenylacid is selected from the group consisting of beta phenylacetic acid, beta phenylacrylic acid, beta phenylcrotonic acid, and mixtures thereof.

Claim 13 (original): The method of Claim 11 wherein said beta phenylacid is selected from the group consisting of beta phenylacetic acid, beta phenylacrylic acid, beta phenylcrotonic acid, and mixtures thereof.

Claim 14 (currently amended): [The method of Claim 5] A method for producing an assembly of substrates comprising:

dispensing a liquid polymeric material on one of a conducting surface on a first substantially planar substrate and a conducting surface on a second substantially planar substrate, the liquid polymeric being disposed inwardly from the edges of the first and the second substrate;

pressing the liquid polymeric material between the first and the second substrate
so that the liquid polymeric material flows towards the edges of the first substrate and the second
substrate; and

curing the liquid polymeric material,

wherein said conducting surface of said first planar substrate includes first
conductive pads, and said conducting surface of said second planar substrate includes second
conductive pads and solder bumps disposed on said second conductive pads,

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wherein said solder bumps comprise a solder material fluxing agent,

wherein said liquid polymeric material comprises a polymer fluxing agent,

wherein said polymer fluxing agent comprises a beta phenylacid and/or a beta phenylhydroxyacid, and

wherein said beta phenylacid comprises beta phenylacrylic acid and said beta phenylhydroxyacid comprises beta phenylhydroxyacrylic acid.

Claim 15 (currently amended): [The method of Claim 5] A method for producing an assembly of substrates comprising:

dispensing a liquid polymeric material on one of a conducting surface on a first substantially planar substrate and a conducting surface on a second substantially planar substrate,
the liquid polymeric being disposed inwardly from the edges of the first and the second substrate;

pressing the liquid polymeric material between the first and the second substrate
so that the liquid polymeric material flows towards the edges of the first substrate and the second
substrate; and

curing the liquid polymeric material,

wherein said conducting surface of said first planar substrate includes first
conductive pads, and said conducting surface of said second planar substrate includes second
conductive pads and solder bumps disposed on said second conductive pads,

wherein said solder bumps includes no solder material fluxing agent and said liquid polymeric material comprises a polymer fluxing agent,

wherein said polymer fluxing agent comprises a beta phenylacid and/or a beta phenylhydroxyacid, and

wherein said beta phenylacid comprises beta phenylacrylic acid and said beta phenylhydroxyacid comprises beta phenylhydroxyacrylic acid.

Claim 16 (original): The method of Claim 1 wherein said liquid polymeric material comprises from about 15% by weight to about 70% by weight of a polymeric resin, from about 15% by weight to about 70% by weight of a curing agent, and from about 0.10% by weight to about 20% by weight of a fluxing agent.

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Claim 17 (withdrawn): A polymeric composition comprising from about 15% by weight to about 70% by weight of a polymeric resin, from about 15% by weight to about 70% by weight of a curing agent, and from about 0.10% by weight to about 20% by weight of a fluxing agent.

Claim 18 (withdrawn): An assembly of substrates comprising a lower substrate; a polymeric composition disposed on said lower substrate; and an upper substrate disposed on said polymeric composition which comprises from about 15% by weight to about 70% by weight of a polymeric resin, from about 15% by weight to about 70% by weight of a curing agent, and from about 0.10% by weight to about 20% by weight of a fluxing agent.

Claim 19 (withdrawn): The polymeric composition of Claim 17 wherein said fluxing agent comprises a beta phenylacid selected from the group consisting of beta phenylacetic acid, beta phenylacrylic acid, beta phenylcrotonic acid, and mixtures thereof.

Claim 20 (withdrawn): The assembly of Claim 18 wherein said fluxing agent comprises a beta phenylacid selected from the group consisting of beta phenylacetic acid, beta phenylacrylic acid, beta phenylcrotonic acid, and mixtures thereof.